

**ADVANCED
POWER
TECHNOLOGY®**
APT50GL60BN 600V 50A

POWER MOS IV™ IGBT

N - CHANNEL ENHANCEMENT MODE HIGH VOLTAGE POWER INSULATED GATE BIPOLAR TRANSISTOR

MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter		APT50GL60BN	UNIT
V_{CES}	Collector-Emitter Voltage		600	Volts
V_{GE}	Gate-Emitter Voltage	± 20		
I_{C1}^*	Continuous Collector Current	50		Amps
I_{C2}	Continuous Collector Current @ $T_C = 90^\circ\text{C}$	30		
I_{CM}	Pulsed Collector Current ①	100		
I_{LM}	Clamped Inductive Load Current @ $T_J = +125^\circ\text{C}$ ②	60		
E_{ARV}	Reverse Voltage Avalanche Energy	100		mJ
P_D	Total Power Dissipation	200		Watts
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150		$^\circ\text{C}$
T_L	Max. Lead Temp. for Soldering: 0.063" from Case for 10 Sec.	300		

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions / Part Number	MIN	TYP	MAX	UNIT
BV_{CES}	Collector-Emitter Breakdown Voltage ($V_{GE} = 0V, I_C = 2.0mA$)	APT50GL60BN	600		Volts
RBV_{CES}	Collector-Emitter Reverse Breakdown Voltage ($V_{GE} = 0V, I_C = -1.0A$)	-15	-25		
$V_{GE(TH)}$	Gate Threshold Voltage ($V_{CE} = V_{GE}, I_C = 1.0mA$)	3		6	
$V_{CE(ON)}$	Collector-Emitter On Voltage ($V_{GE} = 15V, I_C = I_{C2}$)		2.0	2.5	
I_{CES}	Collector Cut-off Current ($V_{CE} = 0.8 V_{CES}, V_{GE} = 0V$)			500	μA
	Collector Cut-off Current ($V_{CE} = 0.8 V_{CES}, V_{GE} = 0V, T_C = 125^\circ\text{C}$)			1.0	mA
I_{GES}	Gate-Emitter Leakage Current ($V_{GE} = \pm 20V, V_{CE} = 0V$)			± 100	nA
$V_{GE}/\Delta T_J$	Gate-Emitter Threshold Voltage Temperature Coefficient		-7.4		mV/ $^\circ\text{C}$
g_{fe}	Forward Transconductance ($V_{CE} = 10V, I_C = I_{C2}$)		14		S

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

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DYNAMIC CHARACTERISTICS

APT50GL60BN

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C _{ies}	Input Capacitance	Capacitance V _{GE} = 0V V _{CE} = 10V f = 1 MHz		2165	2550	pF
C _{oes}	Output Capacitance			440	600	
C _{res}	Reverse Transfer Capacitance			130	200	
Q _g	Total Gate Charge ^③	Gate Charge V _{GE} = 10V V _{CC} = 0.5 V _{CES} I _C = I _{C1}		70	110	nC
Q _{ge}	Gate-Emitter Charge			13	20	
Q _{gc}	Gate-Collector ("Miller") Charge			40	60	
t _d (on)	Turn-on Delay Time	Resistive Switching (25°C) V _{GE} = 15V V _{CC} = 0.5 V _{CES} I _C = I _{C2} R _G = 2Ω		15	30	ns
t _r	Rise Time			50	100	
t _d (off)	Turn-off Delay Time			55	85	
t _f	Fall Time			350	700	
t _d (on)	Turn-on Delay Time	Inductive Switching (125°C) V _{CLAMP} (Peak) = 0.8V _{CES} V _{GE} = 15V I _C = I _{C2} R _G = 2Ω T _J = +125°C		15	30	ns
t _r	Rise Time			15	40	
t _d (off)	Turn-off Delay Time			350	525	
t _f	Fall Time			500	1000	
E _{on}	Turn-on Switching Energy			0.2	0.4	mJ
E _{off}	Turn-off Switching Energy			4.7	9.4	
E _{ts}	Total Switching Losses			4.9	9.8	
t _d (on)	Turn-on Delay Time	Inductive Switching (25°C) V _{CLAMP} (Peak) = 0.8V _{CES} V _{GE} = 15V I _C = I _{C2} R _G = 2Ω T _J = +25°C		15	30	ns
t _r	Rise Time			15	30	
t _d (off)	Turn-off Delay Time			175	350	
t _f	Fall Time			250	500	
E _{ts}	Total Switching Losses			2.5	5	mJ
L _E	Internal Emitter Inductance Measured 5mm/0.197in. From Package			5		nH

THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.625	°C/W
$R_{\theta JA}$	Junction to Ambient			40	
Torque	Mounting Torque using a 6-32 or 3mm Binding Head Machine Screw.		10		in-Lbs.

① Repetitive Rating: Pulse width limited by maximum junction temperature.

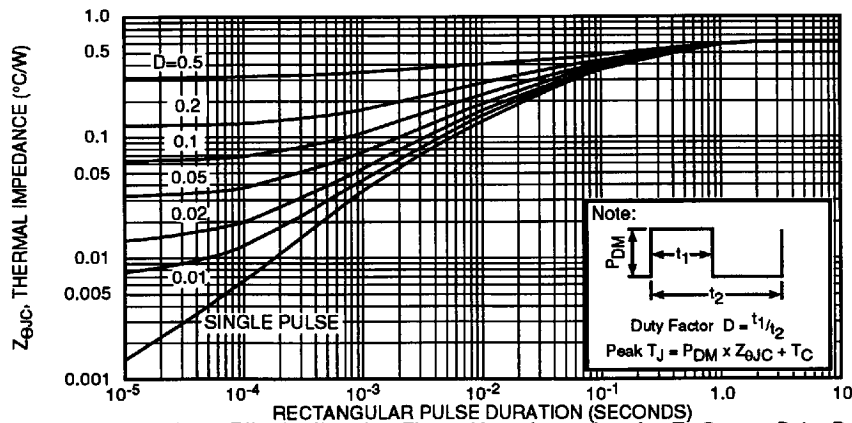
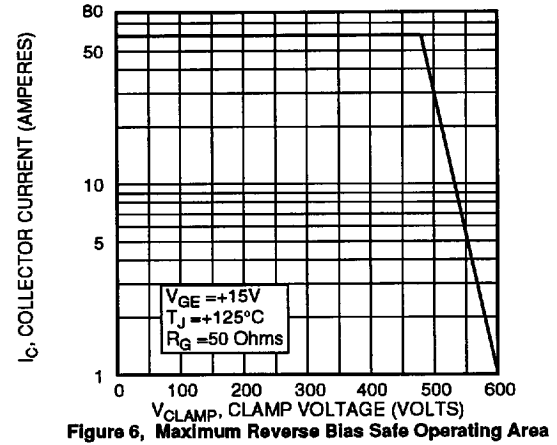
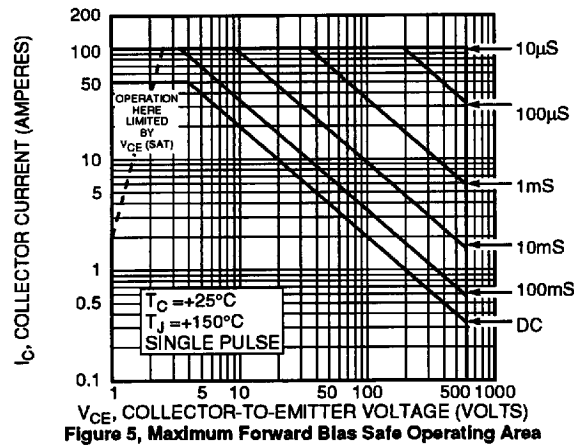
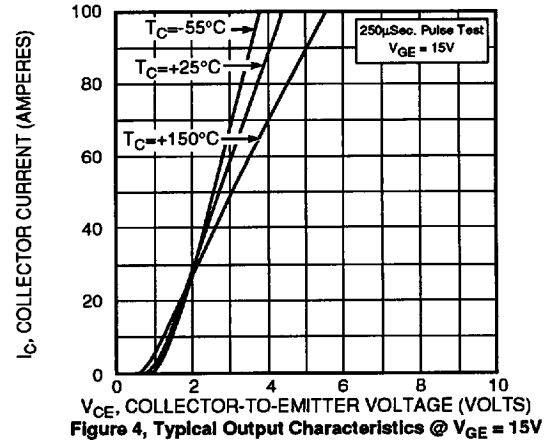
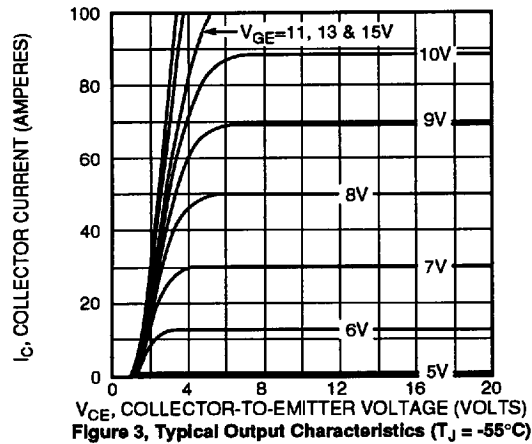
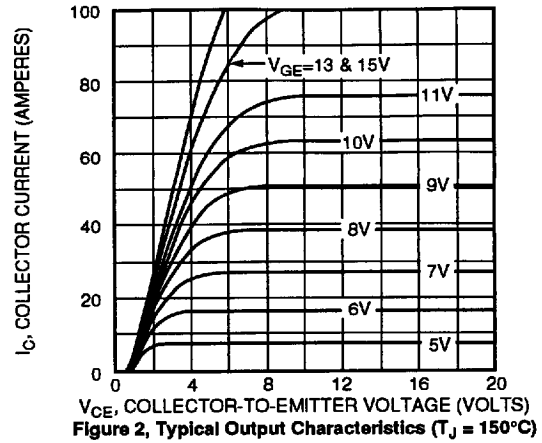
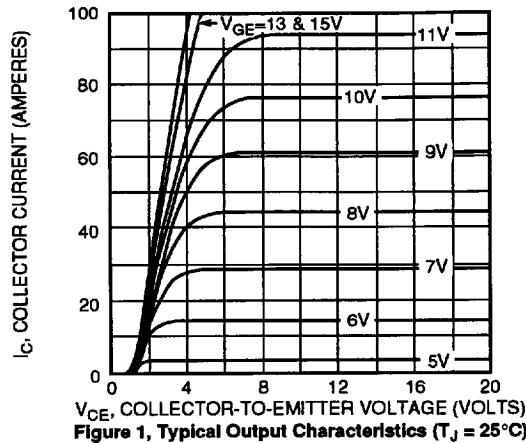
② $V_{CLAMP} = 0.8V_{CES}$ Volts, $R_G = 2\Omega$.

③ See MIL-STD-750 Method 3471

* This product when used in very fast switching circuits (turn-off $dV/dt > 15$ volts per ns) and under operating conditions of $T_c = +150^\circ\text{C}$ and $I_C > I_{C1}$ will latch in a thyristor mode of operation. When device latches, it must be commutated with minimum energy to prevent damage.

APT Reserves the right to change, without notice, the specifications and information contained herein.

APT50GL60BN



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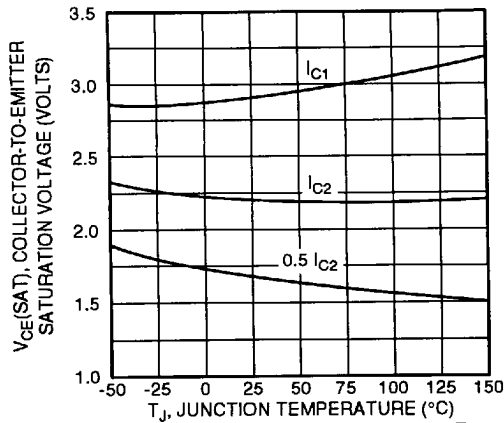


Figure 8, Typical $V_{CE(SAT)}$ Voltage vs Junction Temperature

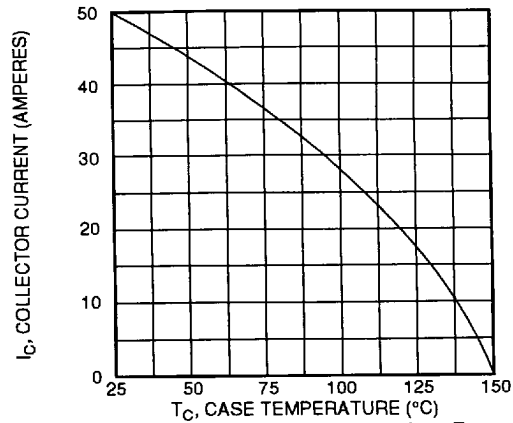


Figure 9, Maximum Collector Current vs Case Temperature

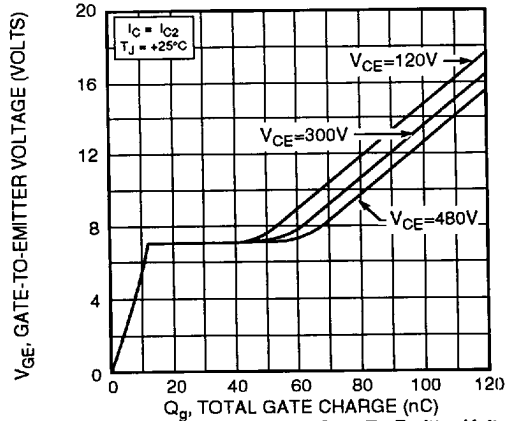


Figure 10, Gate Charges vs Gate-To-Emitter Voltage

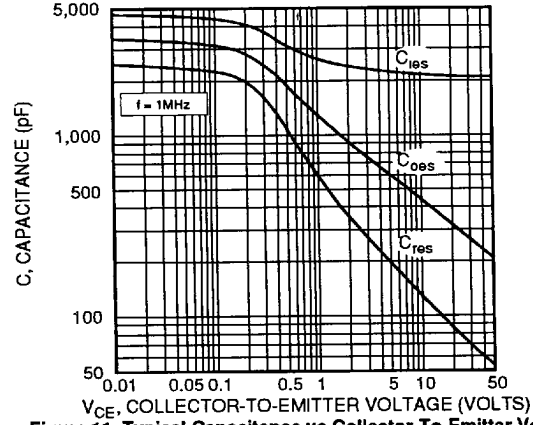


Figure 11, Typical Capacitance vs Collector-To-Emitter Voltage

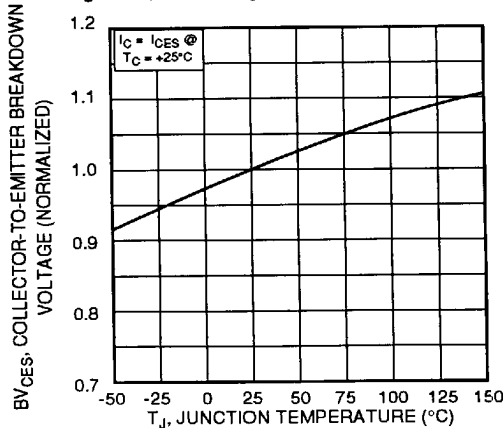


Figure 12, Breakdown Voltage vs Junction Temperature

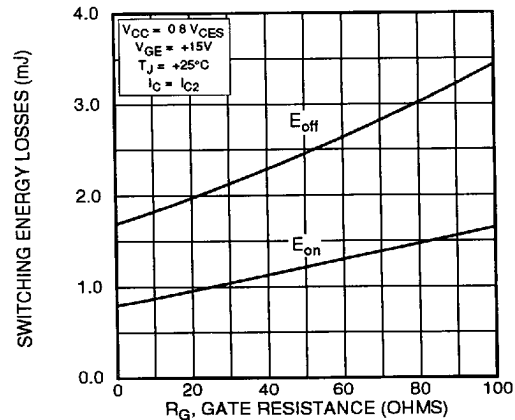


Figure 13, Typical Switching Energy Losses vs Gate Resistance

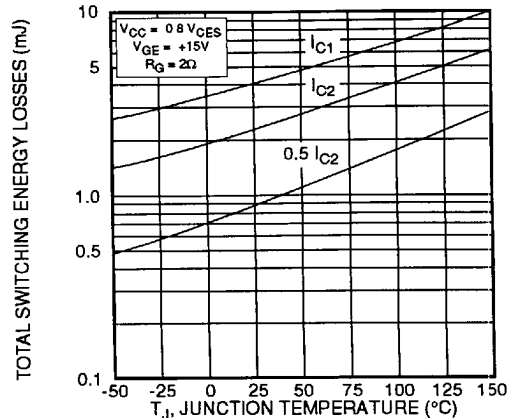


Figure 14, Typical Switching Energy Losses vs. Junction Temperature

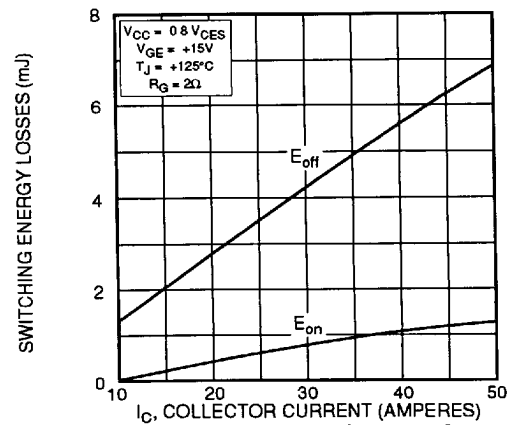


Figure 15, Typical Switching Energy Losses vs Collector Current